



Material Content Data Sheet



Sales Product Name				IPD80N04S3-06		Issued		20. July 2018	
MA#				MA001916240					
Package				PG-TO252-3-11		Weight*		371.34 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.047	0.82	0.82	8206	8206	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	iron	7439-89-6	0.215	0.06		580		
	non noble metal	copper	7440-50-8	215.017	57.90	57.98	579024	579778	
	non noble metal	aluminium	7429-90-5	4.750	1.28	1.28	12792	12792	
wire	non noble metal	aluminium	7429-90-5	4.750	1.28	1.28	12792	12792	
encapsulation	organic material	carbon black	1333-86-4	1.225	0.33		3298		
	plastics	epoxy resin	-	21.429	5.77		57707		
	inorganic material	silicondioxide	60676-86-0	99.799	26.88	32.98	268752	329757	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10072	10072	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245	
solder	non noble metal	tin	7440-31-5	0.055	0.01		149		
	noble metal	silver	7440-22-4	0.069	0.02		186		
	non noble metal	lead	7439-92-1	2.638	0.71	0.74	7104	7439	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51643	51711	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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